

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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SHOU-SHAN FAN	10/12/2011
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PROPERTY NUMBERS Total: 1	
Property Type	Number
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DATE SIGNED:	07/25/2014
Total Attachments: 2	
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PATENT

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. YANG WEI , residing at Beijing, China
- 2. SHOU-SHAN FAN , residing at Beijing, China
- 3. _____ , residing at _____
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **TSINGHUA UNIVERSITY** having a principal place of business at **No.1, Qinghua Yuan, Haidian District, Beijing City, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66, Chung Shan Road, Tu-Cheng Dist., New Taipei City, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **METHOD FOR MAKING SEMICONDUCTOR EPITAXIAL STRUCTURE** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Yang wei</u> YANG WEI	<u>Oct.12,2011</u> Date
2.	<u>Shou Shan Fan</u> SHOU-SHAN FAN	<u>Oct.12,2011</u> Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date